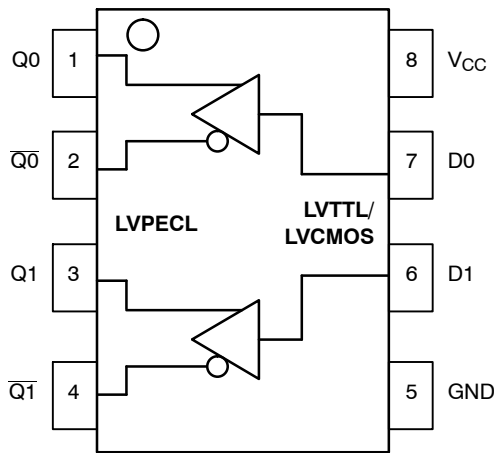


# MC100LVELT22



**Table 1. PIN DESCRIPTION**

PIN	FUNCTION
Qn, $\overline{Qn}$	LVPECL Differential Outputs
D0, D1	LVTTTL/LVCMOS Inputs
V <sub>CC</sub>	Positive Supply
GND	Ground
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

**Figure 1. 8-Lead Pinout (Top View) and Logic Diagram**

EP

**Table 2. ATTRIBUTES**

Characteristics	Value
Internal Input Pulldown Resistor	N/A
Internal Input Pullup Resistor	N/A
ESD Protection Human Body Model Machine Model	> 4 kV > 200 V
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	164
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note AND8003/D.

**Table 3. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	Positive Power Supply	GND = 0 V		7	V
V <sub>I</sub>	Input Voltage	GND = 0 V	V <sub>I</sub> ≤ V <sub>CC</sub>	7	V
I <sub>out</sub>	Output Current	Continuous Surge		50 100	mA mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SO-8 SO-8	190 130	°C/W °C/W
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	std bd	SO-8	41 to 44 ± 5%	°C/W
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W °C/W
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	std bd	TSSOP-8	41 to 44 ± 5%	°C/W
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T <sub>sol</sub>	Wave Solder Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	(Note 2)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

2. JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

# MC100LVELT22

**Table 4. LVPECL DC CHARACTERISTICS**  $V_{CC} = 3.3\text{ V}$ ;  $GND = 0.0\text{ V}$  (Note 3)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{CC}$	Power Supply Current			28			28			29	mA
$V_{OH}$	Output HIGH Voltage (Note 4)	2275		2420	2275		2420	2275		2420	mV
$V_{OL}$	Output LOW Voltage (Note 4)	1490		1680	1490		1680	1490		1680	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Output parameters vary 1:1 with  $V_{CC}$ .  $V_{CC}$  can vary  $\pm 0.15\text{ V}$ .

4. Outputs are terminated through a 50 ohm resistor to  $V_{CC}-2\text{ volts}$ .

**Table 5. LVTTTL/LVCMOS INPUT DC CHARACTERISTICS**  $V_{CC} = 3.3\text{ V}$ ;  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$  (Note 5)

Symbol	Characteristic	Min	Typ	Max	Unit	Condition
$I_{IH}$	Input HIGH Current			20	$\mu\text{A}$	$V_{IN} = 2.7\text{ V}$
$I_{IHH}$	Input HIGH Current			100	$\mu\text{A}$	$V_{IN} = V_{CC}$
$I_{IL}$	Input LOW Current			-0.2	mA	$V_{IN} = 0.5\text{ V}$
$V_{IK}$				-1.2	V	$I_{IN} = -18\text{ mA}$
$V_{IH}$	Input HIGH Voltage	2.0			V	
$V_{IL}$	Input LOW Voltage			0.8	V	

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5.  $V_{CC}$  can vary  $\pm 0.15\text{ V}$ .

**Table 6. AC CHARACTERISTICS**  $V_{CC} = 3.3\text{ V}$ ;  $GND = 0.0\text{ V}$  (Note 6)

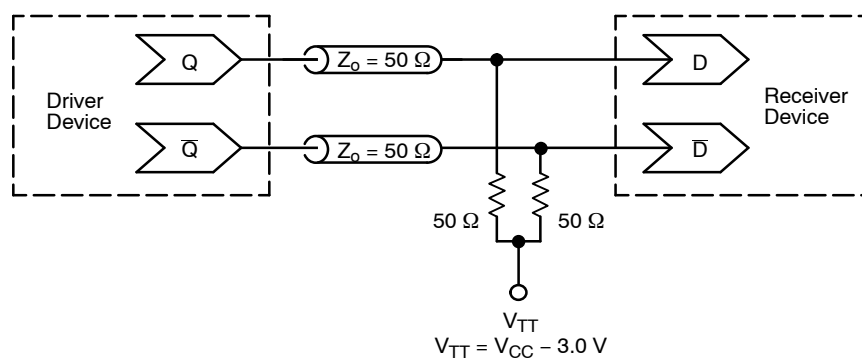
Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{max}$	Maximum Toggle Frequency					350					MHz
$t_{PLH}$	Propagation Delay (Note 7)	200	350	600	200	350	600	200	350	600	ps
$t_{skew}$	Skew Output-to-Output Part-to-Part		30	100 400		30	100 400		30	100 400	ps
$t_{JITTER}$	Random Clock Jitter (RMS)					1.6					ps
$t_r/t_f$	Output Rise/Fall Time (20-80%)	200		550	200		500	200		500	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

6.  $V_{CC}$  can vary  $\pm 0.15\text{ V}$ .

7. Specifications for standard TTL input signal.

## MC100LVELT22



**Figure 1. Typical Termination for Output Driver and Device Evaluation**  
(See Application Note AND8020/D – Termination of ECL Logic Devices.)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC100LVELT22D	SOIC–8	98 Units / Rail
MC100LVELT22DG	SOIC–8 (Pb–Free)	98 Units / Rail
MC100LVELT22DR2	SOIC–8	2500 / Tape & Reel
MC100LVELT22DR2G	SOIC–8 (Pb–Free)	2500 / Tape & Reel
MC100LVELT22DT	TSSOP–8	100 Units / Rail
MC100LVELT22DTG	TSSOP–8 (Pb–Free)	100 Units / Rail
MC100LVELT22DTR2	TSSOP–8	2500 / Tape & Reel
MC100LVELT22DTR2G	TSSOP–8 (Pb–Free)	2500 / Tape & Reel
MC100LVELT22MNR4	DFN8	1000 / Tape & Reel
MC100LVELT22MNRG	DFN8 (Pb–Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

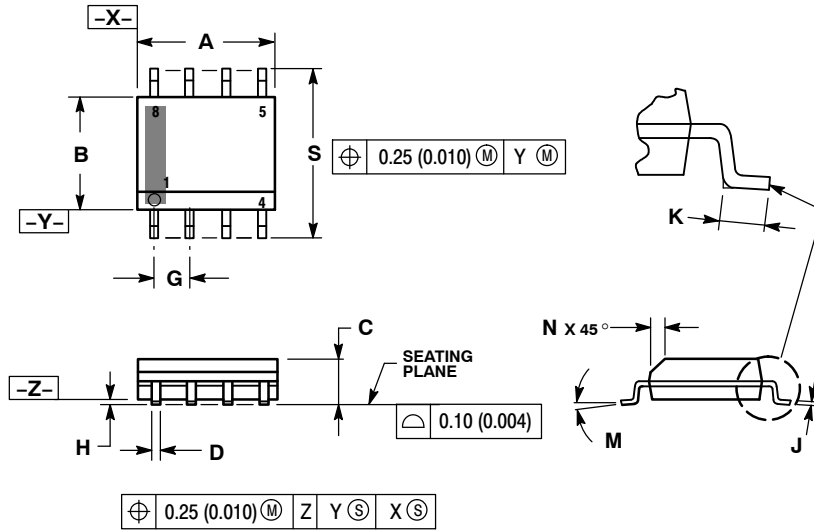
### Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

# MC100LVELT22

## PACKAGE DIMENSIONS

SOIC-8 NB  
CASE 751-07  
ISSUE AH

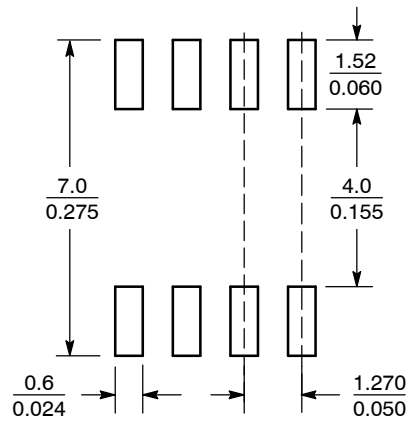


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

## SOLDERING FOOTPRINT\*



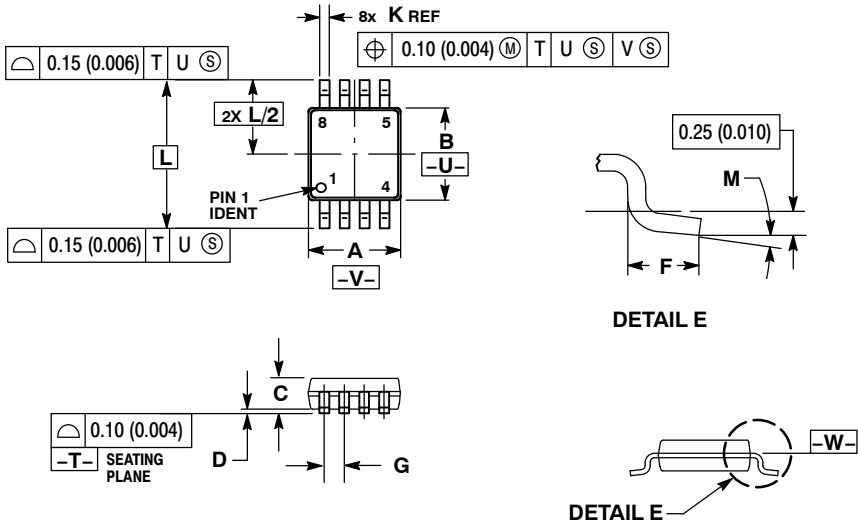
SCALE 6:1 (mm/inches)

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC100LVELT22

PACKAGE DIMENSIONS

TSSOP-8  
DT SUFFIX  
PLASTIC TSSOP PACKAGE  
CASE 948R-02  
ISSUE A



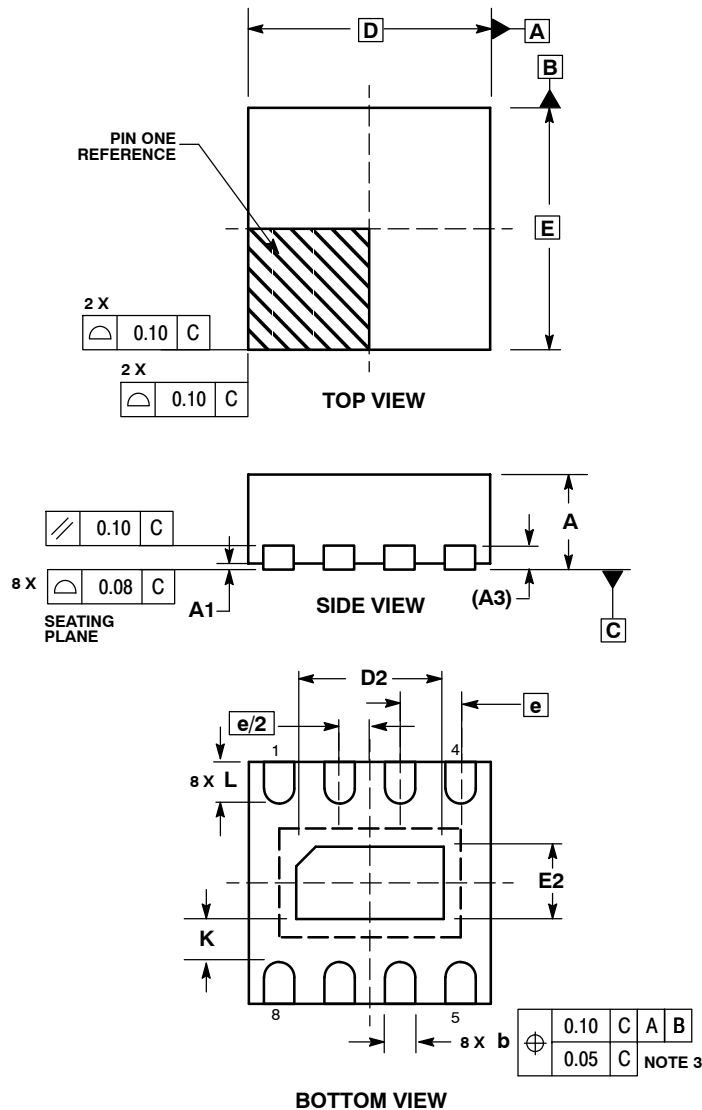
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

# MC100LVELT22

## PACKAGE DIMENSIONS

DFN8  
CASE 506AA-01  
ISSUE D



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	2.00	BSC
D2	1.10	1.30
E	2.00	BSC
E2	0.70	0.90
e	0.50	BSC
K	0.20	---
L	0.25	0.35

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